



HT1622

RAM Mapping 32×8 LCD Controller for I/O MCU

Features

- Operating voltage: 2.7V~5.2V
- · Built-in RC oscillator
- 1/4 bias, 1/8 duty, frame frequency is 64Hz
- Max. 32×8 patterns, 8 commons, 32 segments
- · Built-in internal resistor type bias generator
- · 3-wire serial interface
- 8 kinds of time base or WDT selection
- · Time base or WDT overflow output
- Built-in LCD display RAM

- R/W address auto increment
- Two selectable buzzer frequencies (2kHz or 4kHz)
- Power down command reduces power consumption
- · Software configuration feature
- Data mode and Command mode instructions
- Three data accessing modes
- · VLCD pin to adjust LCD operating voltage
- Cascade application
- 64-pin QFP package

General Description

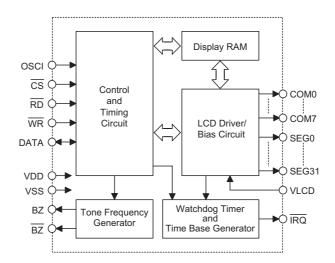
HT1622 is a peripheral device specially designed for I/O type MCU used to expand the display capability. The max. display segment of the device are 256 patterns (32×8). It also supports serial interface, buzzer sound, Watchdog Timer or time base timer functions. The HT1622 is a memory mapping and multi-function LCD controller. The software configuration feature of the

HT1622 make it suitable for multiple LCD applications including LCD modules and display subsystems. Only three lines are required for the interface between the host controller and the HT1622. The HT162X series have many kinds of products that match various applications

Selection Table

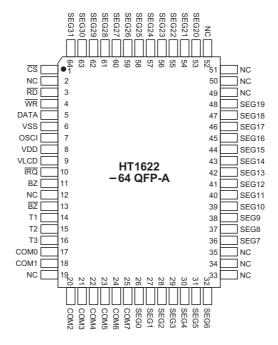
HT162X	HT1620	HT1621	HT1622	HT16220	HT1623	HT1625	HT1626
СОМ	4	4	8	8	8	8	16
SEG	32	32	32	32	48	64	48
Built-in Osc.	_	√	√	_	√	√	V
Crystal Osc.	√	√	_	√	√	√	V

Block Diagram

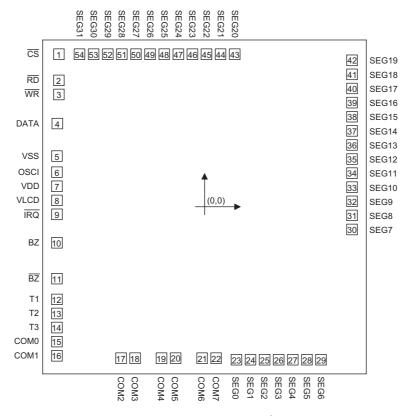




Pin Assignment



Pad Assignment



Chip size: $149 \times 155 \text{ (mil)}^2$

^{*} The IC substrate should be connected to VDD in the PCB layout artwork.



Pad Coordinates Unit: mil

Pad No.	Х	Υ	Pad No.	Х	Υ
1	-68.43	71.78	28	48.15	-71.91
2	-68.43	59.46	29	54.78	-71.91
3	-68.43	52.83	30	69.32	-10.67
4	-69.19	39.14	31	69.32	-4.04
5	-69.36	23.89	32	69.32	2.59
6	-69.36	16.32	33	69.32	9.22
7	-69.36	9.69	34	69.32	15.85
8	-69.36	3.06	35	69.32	22.48
9	-69.36	-3.57	36	69.32	29.11
10	-69.36	-16.92	37	69.32	35.74
11	-69.36	-33.83	38	69.32	42.37
12	-69.36	-43.52	39	69.32	49.00
13	-69.36	-50.15	40	69.32	55.63
14	-69.36	-56.78	41	69.32	62.26
15	-69.36	-63.41	42	69.32	68.89
16	-69.36	-70.04	43	14.19	71.78
17	-39.23	-71.14	44	7.57	71.78
18	-32.60	-71.14	45	0.94	71.78
19	-20.19	-71.14	46	-5.70	71.78
20	-13.56	-71.14	47	-12.32	71.78
21	-1.15	-71.14	48	-18.95	71.78
22	5.48	-71.14	49	-25.58	71.78
23	15.00	-71.91	50	-32.22	71.78
24	21.63	-71.91	51	-38.85	71.78
25	28.26	-71.91	52	-45.47	71.78
26	34.89	-71.91	53	-52.10	71.78
27	41.52	-71.91	54	-58.74	71.78

Pad Description

Pad No.	Pad Name	I/O	Description
1	CS	I	Chip selection input with Pull-high resistor. When the $\overline{\text{CS}}$ is logic high, the data and command read from or written to the HT1622 are disabled. The serial interface circuit is also reset. But if $\overline{\text{CS}}$ is at logic low level and is input to the $\overline{\text{CS}}$ pad, the data and command transmission between the host controller and the HT1622 are all enabled.
2	RD	I	READ clock input with Pull-high resistor. Data in the RAM of the HT1622 are clocked out on the falling edge of the $\overline{\text{RD}}$ signal. The clocked out data will appear on the data line. The host controller can use the next rising edge to latch the clocked out data.
3	WR	ı	WRITE clock input with Pull-high resistor. Data on the DATA line are latched into the HT1622 on the rising edge of the \overline{WR} signal.
4	DATA	I/O	Serial data input or output with Pull-high resistor
5	VSS	_	Negative power supply, ground
6	OSCI	ı	If the system clock comes from an external clock source, the external clock source should be connected to the OSCI pad.
7	VDD	_	Positive power supply
8	VLCD	ı	LCD operating voltage input pad
9	ĪRQ	0	Time base or Watchdog Timer overflow flag, NMOS open drain output
10, 11	BZ, BZ	0	2kHz or 4kHz tone frequency output pair
12~14	T1~T3	I	Not connected
15~22	COM0~COM7	0	LCD common outputs
23~54	SEG0~SEG31	0	LCD segment outputs



Absolute Maximum Ratings

Supply Voltage	V _{SS} -0.3V to V _{SS} +5.5V	Storage Temperature	50°C to 125°C
Input Voltage	V_{SS} -0.3V to V_{DD} +0.3V	Operating Temperature	40°C to 85°C

Note: These are stress ratings only. Stresses exceeding the range specified under "Absolute Maximum Ratings" may cause substantial damage to the device. Functional operation of this device at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.

D.C. Characteristics Ta=25°C

Symbol	Parameter	Parameter Test Conditions		Min.	Тур.	Max.	Unit
Symbol	raiametei	V _{DD}	Conditions	IVIIII.	ıyρ.	IVIAA.	Oilit
V _{DD}	Operating Voltage	_	_	2.7	—	5.2	V
1	Operating Current		No load or LCD ON	_	80	210	μА
I _{DD1}	Operating Current	5V	On-chip RC oscillator	_	135	415	μΑ
	On a realization Commont	3V	No load or LCD OFF	_	8	30	μΑ
I _{DD2}	Operating Current	5V	On-chip RC oscillator	_	20	55	μΑ
	21 11 2	3V		_	1	8	μА
I _{STB}	Standby Current	5V	No load, Power down mode	_	2	16	μА
.,		3V	DATA W/D 00 DD	0	_	0.6	V
V _{IL}	Input Low Voltage	5V	DATA, WR, CS, RD	0	_	1.0	V
.,		3V		2.4	_	3	V
V _{IH}	Input High Voltage	5V	DATA, WR, CS, RD	4.0	_	5	V
		3V	V _{OL} =0.3V	0.9	1.8	_	mA
I _{OL1}	$BZ, \overline{BZ}, \overline{IRQ}$	5V	V _{OL} =0.5V	1.7	3	_	mA
	=	3V	V _{OH} =2.7V	-0.9	-1.8	_	mA
I _{OH1}	BZ, BZ	5V	V _{OH} =4.5V	-1.7	-3	_	mA
		3V	V _{OL} =0.3V	200	450	_	μА
I _{OL1}	DATA	5V	V _{OL} =0.5V	250	500	_	μА
		3V	V _{OH} =2.7V	-200	-450	_	μА
I _{OH1}	DATA	5V	V _{OH} =4.5V	-250	-500	_	μА
		3V	V _{OL} =0.3V	15	40	_	μА
I _{OL2}	LCD Common Sink Current	5V	V _{OL} =0.5V	100	200	_	μА
		3V	V _{OH} =2.7V	-15	-30	_	μА
I _{OH2}	LCD Common Source Current	5V	V _{OH} =4.5V	-45	-90	_	μА
		3V	V _{OL} =0.3V	15	30	_	μА
I _{OL3}	LCD Segment Sink Current	5V	V _{OL} =0.5V	70	150	_	μА
	1000	3V	V _{OH} =2.7V	-6	-13	_	μА
I _{OH3}	LCD Segment Source Current	5V	V _{OH} =4.5V	-20	-40	_	μА
Б	B #111 B 11	3V	DATA W/D 00 00	100	200	300	kΩ
R _{PH}	Pull-high Resistor	5V	DATA, WR, CS, RD	50	100	150	kΩ
	<u> </u>						

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A.C. Characteristics

Ta=25°C

Symbol	Parameter		Test Conditions	BAI:	T		Unit
Symbol	Parameter	V_{DD}	Conditions	Min.	Тур.	Max.	Unit
f _{SYS1}	System Clock	3V	On-chip RC oscillator	22	32	40	kHz
		5V		24	32	40	kHz
£		3V		_	32	_	kHz
f _{SYS2}	System Clock	5V	External clock source	_	32	_	kHz
f	LCD Farms Farming	3V	On ahin DC assillator	44	64	80	Hz
f _{LCD1}	LCD Frame Frequency	5V	On-chip RC oscillator	48	64	80	Hz
ſ	LCD Frame Frequency		F. (_	64	_	_
f _{LCD2}			External clock source	_	64	_	_
t _{COM}	LCD Common Period	_	n: Number of COM	_	n/f _{LCD}	_	sec
,			5 500/	_	_	150	kHz
f _{CLK1}	Serial Data Clock (WR pin)	5V	Duty cycle 50%	_	_	300	kHz
		3V		_	_	75	kHz
f _{CLK2}	Serial Data Clock (RD pin)	5V	Duty cycle 50%		_	150	kHz
t _{CS}	Serial Interface Reset Pulse Width (Figure 3)	_	CS	_	250	_	ns
			Write mode	3.34	_	_	
		3V	Read mode	6.67	_	_	μS
t _{CLK}	WR, RD Input Pulse Width (Figure 1)		Write mode	1.67	_	_	
		5V	Read mode	3.34	_	_	μS
	Rise/Fall Time Serial Data Clock Width	3V			400		
t_r , t_f	(Figure 1)	5V	_	_	120	_	ns
t _{su}	Setup Time for DATA to WR, RD Clock	3V			120		no
^L Su	Width (Figure 2)	5V	_		120		ns
t _h	Hold Time for DATA to $\overline{\text{WR}}$, $\overline{\text{RD}}$, Clock	3V			120		ns
11	Width (Figure 2)		_		120		113
t _{su1}	Setup Time for $\overline{\text{CS}}$ to $\overline{\text{WR}}$, $\overline{\text{RD}}$ Clock		_	_	100	_	ns
-Su I	Width (Figure 3)	5V	_				
t _{h1}	Hold Time for $\overline{\text{CS}}$ to $\overline{\text{WR}}$, $\overline{\text{RD}}$ Clock	3V 5V	_	_	100	_	ns
	Width (Figure 3)				100		ns

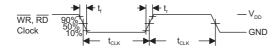


Figure 1

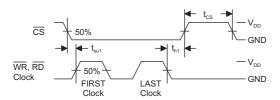


Figure 3

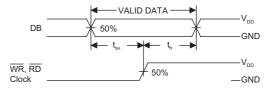


Figure 2



RC Oscillator Frequency Deviation

Operating Temperature	-40°C	0°C	25°C	70°C	75°C	80°C	85°C
Average Deviation	19.85%	2.98%	0	-21.14%	-22.50%	-23.82%	-25.35%

Functional Description

Display Memory - RAM Structure

The static display RAM is organized into 64×4 bits and stores the display data. The contents of the RAM are directly mapped to the contents of the LCD driver. Data in the RAM can be accessed by the READ, WRITE and READ-MODIFY-WRITE commands. The following is a mapping from the RAM to the LCD patterns.

Time Base and Watchdog Timer (WDT)

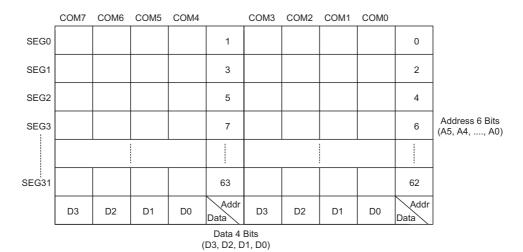
The time base generator and WDT share the same divided (± 256) counter. TIMER DIS/EN/CLR, WDT DIS/EN/CLR and $\overline{\text{IRQ}}$ EN/DIS are independent from each other. Once the WDT time-out occurs, the $\overline{\text{IRQ}}$ pin will

remain at logic low level until the CLR WDT or the $\overline{\mbox{IRQ}}$ DIS command is issued.

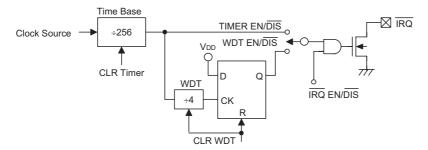
If an external clock is selected as the source of system frequency, the SYS DIS command turns out invalid and the power down mode fails to be carried out until the external clock source is removed.

Buzzer Tone Output

A simple tone generator is implemented in the HT1622. The tone generator can output a pair of differential driving signals on the BZ and $\overline{\text{BZ}}$ which are used to generate a single tone.



RAM Mapping



Timer and WDT Configurations



Command Format

The HT1622 can be configured by the software setting. There are two mode commands to configure the HT1622 resource and to transfer the LCD display data.

The following are the data mode ID and the command mode ID:

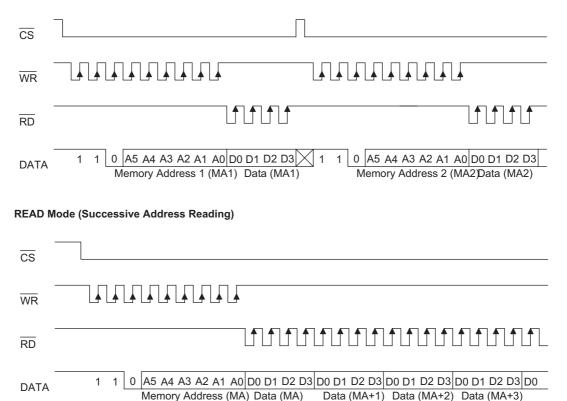
Operation	Mode	ID
READ	Data	110
WRITE	Data	101
READ-MODIFY-WRITE	Data	101
COMMAND	Command	100

If successive commands have been issued, the command mode ID can be omitted. While the system is operating in a non-successive command or a non-successive address data mode, the $\overline{\text{CS}}$ pin should be set to "1" and the previous operation mode will be reset also. The $\overline{\text{CS}}$ pin returns to "0", a new operation mode ID should be issued first.

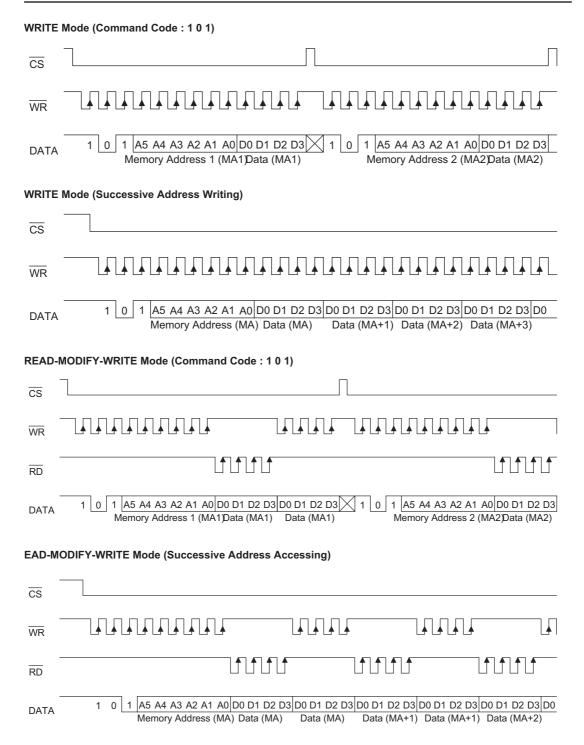
Name Command Code		Function
TONE OFF	0000-1000-X	Turn-off tone output
TONE 4K	010X-XXXX-X	Turn-on tone output, tone frequency is 4kHz
TONE 2K	0110-XXXX-X	Turn-on tone output, tone frequency is 2kHz

Timing Diagrams

READ Mode (Command Code: 110)

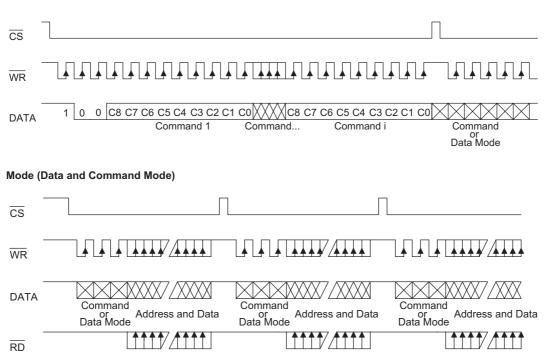






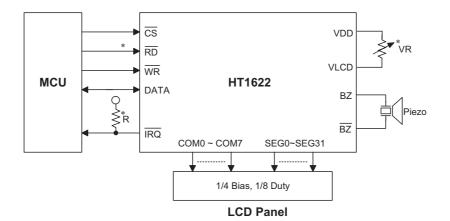


Command Mode (Command Code: 100)





Application Circuits



Note: The connection of $\overline{\text{IRQ}}$ and $\overline{\text{RD}}$ pin can be selected depending on the requirement of the MCU.

The voltage applied to V_{LCD} pin must be lower than V_{DD} .

Adjust VR to fit LCD display, at V_{DD}=5V, V_{LCD}=4V, VR=15k $\Omega\pm20\%$.

Adjust R (external pull-high resistance) to fit user's time base clock.

Command Summary

Name	ID	Command Code	D/C	Function	Def.
READ	110	A5A4A3A2A1A0D0D1D2D3	D	Read data from the RAM	
WRITE	101	A5A4A3A2A1A0D0D1D2D3	D	Write data to the RAM	
READ-MODIFY- WRITE	101	A5A4A3A2A1A0D0D1D2D3	D	Read and Write data to the RAM	
SYS DIS	100	0000-0000-X	С	Turn off both system oscillator and LCD bias generator	Yes
SYS EN	100	0000-0001-X	С	Turn on system oscillator	
LCD OFF	100	0000-0010-X	С	Turn off LCD display	Yes
LCD ON	100	0000-0011-X	С	Turn on LCD display	
TIMER DIS	100	0000-0100-X	С	Disable time base output	Yes
WDT DIS	100	0000-0101-X	С	Disable WDT time-out flag output	Yes
TIMER EN	100	0000-0110-X	С	Enable time base output	
WDT EN	100	0000-0111-X	С	Enable WDT time-out flag output	
TONE OFF	100	0000-1000-X	С	Turn off tone outputs	Yes
CLR TIMER	100	0000-1101-X	С	Clear the contents of the time base generator	
CLR WDT	100	0000-1111-X	С	Clear the contents of WDT stage	
RC 32K	100	0001-10XX-X	С	System clock source, on-chip RC oscillator	Yes
EXT 32K	100	0001-11XX-X	С	System clock source, external clock source	
TONE 4K	100	010X-XXXX-X	С	Tone frequency output: 4kHz	
TONE 2K	100	0110-XXXX-X	С	Tone frequency output: 2kHz	
ĪRQ DIS	100	100X-0XXX-X	С	Disable IRQ output	Yes
ĪRQ EN	100	100X-1XXX-X	С	Enable IRQ output	

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Name	ID	Command Code	D/C	Function	Def.
F1	100	101X-0000-X	С	Time base clock output: 1Hz The WDT time-out flag after: 4s	
F2	100	101X-0001-X	С	Time base clock output: 2Hz The WDT time-out flag after: 2s	
F4	100	101X-0010-X	С	Time base clock output: 4Hz The WDT time-out flag after: 1s	
F8	100	101X-0011-X	С	Time base clock output: 8Hz The WDT time-out flag after: 1/2s	
F16	100	101X-0100-X	С	Time base clock output: 16Hz The WDT time-out flag after: 1/4s	
F32	100	101X-0101-X	С	Time base clock output: 32Hz The WDT time-out flag after: 1/8s	
F64	100	101X-0110-X	С	Time base clock output: 64Hz The WDT time-out flag after: 1/16s	
F128	100	101X-0111-X	С	Time base clock output: 128Hz The WDT time-out flag after: 1/32s	Yes
TEST	100	1110-0000-X	С	Test mode, user don't use.	
NORMAL	100	1110-0011-X	С	Normal mode	Yes

Note: X: Don't care

A5~A0 : RAM address D3~D0 : RAM data

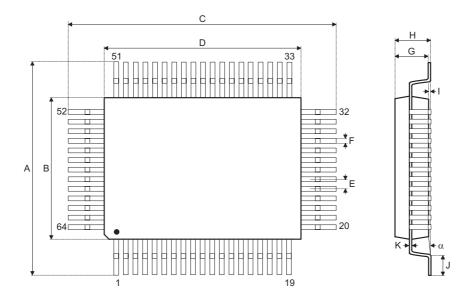
D/C : Data/Command mode
Def. : Power on reset default

All the bold forms, namely **1 1 0, 1 0 1**, and **1 0 0**, are mode commands. Of these, **1 0 0** indicates the command mode ID. If successive commands have been issued, the command mode ID except for the first command will be omitted. The source of the tone frequency and of the time base or WDT clock frequency can be derived from an on-chip 32kHz RC oscillator or an external 32kHz clock. Calculation of the frequency is based on the system frequency sources as stated above. It is recommended that the host controller should initialize the HT1622 after power on reset, for power on reset may fail, which in turn leads to the malfunctioning of the HT1622.



Package Information

64-pin QFP (14×20) Outline Dimensions



Complete	Dimensions in mm						
Symbol	Min.	Nom.	Max.				
Α	18.80	_	19.20				
В	13.90	_	14.10				
С	24.80	_	25.20				
D	19.90	_	20.10				
E	_	1	_				
F	_	0.40	_				
G	2.50		3.10				
Н	_	_	3.40				
1	_	0.10					
J	1.15		1.45				
K	0.10	_	0.20				
α	0°	_	7°				



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